

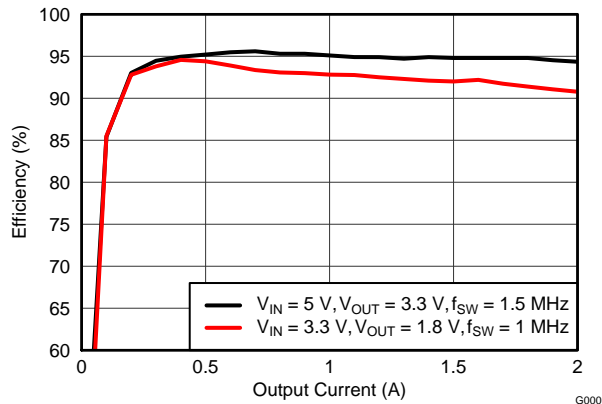
TPS84210 2.95V 至 6V 输入、2A 同步降压集成式电源解决方案

1 特性

- 完整的集成式电源解决方案可实现小尺寸和扁平设计
- 效率高达 96%
- 宽输出电压调节范围 0.8V 至 3.6V，基准精度为 $\pm 1\%$
- 可调开关频率 (500kHz 至 2MHz)
- 与外部时钟同步
- 可调节缓启动
- 输出电压排序/跟踪
- 电源正常输出
- 可编程欠压闭锁 (UVLO)
- 输出过流保护
- 过热保护
- 运行温度范围: -40°C 至 85°C
- 增强的散热性能: $12^{\circ}\text{C}/\text{W}$
- 符合 EN55022 B 类辐射标准
- 要获得包括 SwitcherPro™ 在内的设计帮助，请访问 <http://www.ti.com/TPS84210>

2 应用范围

- 宽带和通信基础设施
- 自动化测试和医疗设备
- 紧凑型外设组件互连接口 (PCI) / PCI 快速接口 / PCI 扩展 (PXI) 快速接口
- DSP 和 FPGA 负载点应用
- 高密度分布式电源系统



3 说明

TPS84210RKG 是一个简单易用的集成式电源解决方案，它在一个小外形尺寸的 BQFN 封装内整合了一个带有功率 MOSFET 的 2A 直流/直流转换器、一个电感器以及无源器件。这个整体电源解决方案仅需 3 个外部组件，并免除了环路补偿和磁性元件选择过程。

9x11x2.8mm BQFN 封装能轻松焊接到印制电路板上，并且可实现效率高于 90% 的紧凑型负载点设计且具有结至环境的热阻仅为 $12^{\circ}\text{C}/\text{W}$ 的出色功率耗散。在环境温度为 85°C 且无气流的情况下，该器件可提供 2A 的满额输出电流。

TPS84210 具有离散式负载点设计的灵活性和功能集，是为高性能 DSP 和 FPGA 供电的理想选择。先进的封装技术可提供一个与标准 QFN 贴装和测试技术兼容的耐用且可靠的电源解决方案。

简化的应用

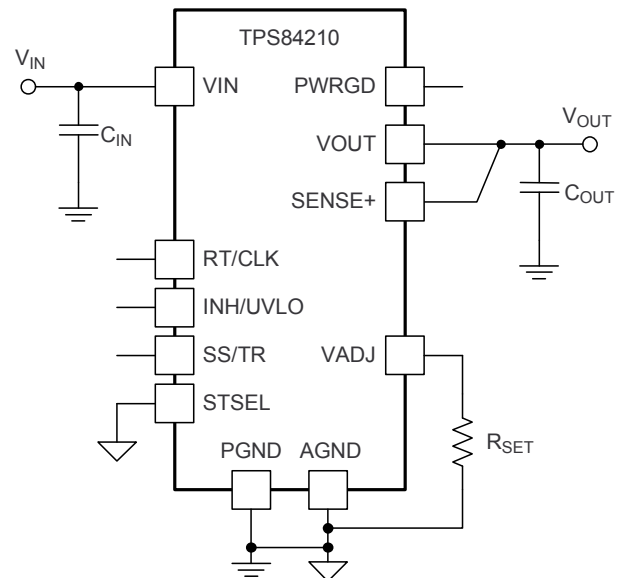


Table 1. ORDERING INFORMATION⁽¹⁾

TA	PACKAGE	ORDERABLE NUMBER	PINS	TRANSPORT MEDIA	MINIMUM QUANTITY	ECO PLAN
-40°C to 85°C	Plastic Quad Flat Pack (BQFN)	TPS84210RKGR	39	Tape and Reel	500	Green (RoHS and no Sb/Br)
-40°C to 85°C		TPS84210RKGT		Tape and Reel	250	Green (RoHS and no Sb/Br)

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this datasheet, or see the TI website at www.ti.com.

4 Specifications

4.1 ABSOLUTE MAXIMUM RATINGS⁽¹⁾ over operating temperature range (unless otherwise noted)

		VALUE		UNIT
		MIN	MAX	
Input Voltage	VIN, PWRGD	-0.3	7	V
	INH/UVLO, RT/CLK	-0.3	3.3	V
	SS/TR, STSEL, VADJ	-0.3	3	V
	SENSE+ VADJ rating must also be met	-0.3	VOUT	V
Output Voltage	PH	-0.6	7	V
	PH 10ns Transient	-2	7	V
	VOUT	-0.6	VIN	V
V _{DIFF} (GND to exposed thermal pad)		-0.2	0.2	V
Source Current	RT/CLK, INH/UVLO		±100	µA
	PH		Current Limit	A
Sink Current	PH		Current Limit	A
	SS/TR		±100	µA
	PWRGD		10	mA
Operating Junction Temperature		-40	125 ⁽²⁾	°C
Storage Temperature		-65	150	°C
Peak Reflow Case Temperature ⁽³⁾			240	°C
Maximum Number of Reflows Allowed ⁽³⁾			1	
Mechanical Shock	Mil-STD-883D, Method 2002.3, 1 msec, 1/2 sine, mounted		1500	G
Mechanical Vibration	Mil-STD-883D, Method 2007.2, 20-2000Hz		20	

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) See the temperature derating curves in the Typical Characteristics section for thermal information.

(3) For soldering specifications, refer to the [Soldering Requirements for BQFN Packages](#) application note.

4.2 THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		TPS84210	UNIT
		RKG39	
		39 PINS	
θ_{JA}	Junction-to-ambient thermal resistance ⁽²⁾	12	°C/W
ψ_{JT}	Junction-to-top characterization parameter ⁽³⁾	2.2	
ψ_{JB}	Junction-to-board characterization parameter ⁽⁴⁾	9.7	

- (1) For more information about traditional and new thermal metrics, see the IC Package Thermal Metrics application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance, θ_{JA} , applies to devices soldered directly to a 100 mm x 100 mm double-sided PCB with 1 oz. copper and natural convection cooling. Additional airflow reduces θ_{JA} .
- (3) The junction-to-top characterization parameter, ψ_{JT} , estimates the junction temperature, T_J , of a device in a real system, using a procedure described in JESD51-2A (sections 6 and 7). $T_J = \psi_{JT} * P_{dis} + T_T$; where P_{dis} is the power dissipated in the device and T_T is the temperature of the top of the device.
- (4) The junction-to-board characterization parameter, ψ_{JB} , estimates the junction temperature, T_J , of a device in a real system, using a procedure described in JESD51-2A (sections 6 and 7). $T_J = \psi_{JB} * P_{dis} + T_B$; where P_{dis} is the power dissipated in the device and T_B is the temperature of the board 1mm from the device.

4.3 PACKAGE SPECIFICATIONS

TPS84210		UNIT
Weight		0.85 grams
Flammability	Meets UL 94 V-O	
MTBF Calculated reliability	Per Bellcore TR-332, 50% stress, $T_A = 40^\circ\text{C}$, ground benign	38.5 Mhrs

4.4 ELECTRICAL CHARACTERISTICS

 Over -40°C to 85°C free-air temperature, $V_{\text{IN}} = 3.3\text{ V}$, $V_{\text{OUT}} = 1.8\text{ V}$, $I_{\text{OUT}} = 2\text{ A}$,

 $C_{\text{IN}1} = 47\text{ }\mu\text{F}$ ceramic, $C_{\text{IN}2} = 220\text{ }\mu\text{F}$ poly-tantalum, $C_{\text{OUT}1} = 47\text{ }\mu\text{F}$ ceramic, $C_{\text{OUT}2} = 100\text{ }\mu\text{F}$ poly-tantalum (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
I_{OUT}	Output current	$T_{\text{A}} = 85^{\circ}\text{C}$, natural convection	0		2	A	
V_{IN}	Input voltage range	Over I_{OUT} range	2.95 ⁽¹⁾		6	V	
$UVLO$	V_{IN} Undervoltage lockout	$V_{\text{IN}} = \text{increasing}$		3.05	3.135	V	
		$V_{\text{IN}} = \text{decreasing}$	2.5	2.75			
$V_{\text{OUT(aj)}}$	Output voltage adjust range	Over I_{OUT} range	0.8		3.6	V	
V_{OUT}	Set-point voltage tolerance	$T_{\text{A}} = 25^{\circ}\text{C}$, $I_{\text{OUT}} = 0\text{ A}$			$\pm 1.0\%$ ⁽²⁾		
	Temperature variation	$-40^{\circ}\text{C} \leq T_{\text{A}} \leq +85^{\circ}\text{C}$, $I_{\text{OUT}} = 0\text{ A}$		$\pm 0.3\%$			
	Line regulation	Over V_{IN} range, $T_{\text{A}} = 25^{\circ}\text{C}$, $I_{\text{OUT}} = 0\text{ A}$		$\pm 0.1\%$			
	Load regulation	Over I_{OUT} range, $T_{\text{A}} = 25^{\circ}\text{C}$		$\pm 0.1\%$			
	Total output voltage variation	Includes set-point, line, load, and temperature variation				$\pm 1.5\%$ ⁽²⁾	
η	Efficiency	$V_{\text{IN}} = 5\text{ V}$ $I_{\text{O}} = 1\text{ A}$	$V_{\text{OUT}} = 3.3\text{ V}$, $f_{\text{SW}} = 1.5\text{ MHz}$		95%		
			$V_{\text{OUT}} = 2.5\text{ V}$, $f_{\text{SW}} = 1.5\text{ MHz}$		93%		
			$V_{\text{OUT}} = 1.8\text{ V}$, $f_{\text{SW}} = 1\text{ MHz}$		92%		
			$V_{\text{OUT}} = 1.5\text{ V}$, $f_{\text{SW}} = 1\text{ MHz}$		91%		
			$V_{\text{OUT}} = 1.2\text{ V}$, $f_{\text{SW}} = 750\text{ kHz}$		90%		
			$V_{\text{OUT}} = 1.0\text{ V}$, $f_{\text{SW}} = 650\text{ kHz}$		88%		
		$V_{\text{IN}} = 3.3\text{ V}$ $I_{\text{O}} = 1\text{ A}$	$V_{\text{OUT}} = 1.8\text{ V}$, $f_{\text{SW}} = 1\text{ MHz}$		93%		
			$V_{\text{OUT}} = 1.5\text{ V}$, $f_{\text{SW}} = 1\text{ MHz}$		92%		
			$V_{\text{OUT}} = 1.2\text{ V}$, $f_{\text{SW}} = 750\text{ kHz}$		91%		
			$V_{\text{OUT}} = 1.0\text{ V}$, $f_{\text{SW}} = 650\text{ kHz}$		89%		
			$V_{\text{OUT}} = 0.8\text{ V}$, $f_{\text{SW}} = 650\text{ kHz}$		87%		
	Output voltage ripple	20 MHz bandwidth		9		mV _{PP}	
I_{LIM}	Overcurrent threshold			3.5		A	
	Transient response	1.0 A/ μs load step from 0.5A to 1.5A	Recovery time		80	μs	
			V_{OUT} over/undershoot		45	mV	
$V_{\text{INH-H}}$	Inhibit Control	Inhibit High Voltage		1.25	Open ⁽³⁾	V	
$V_{\text{INH-L}}$		Inhibit Low Voltage	-0.3	1.0			
$I_{\text{I(stby)}}$	Input standby current	INH pin to AGND		70	100	μA	
Power Good	PWRGD Thresholds	V_{OUT} rising	Good		93%		
			Fault		107%		
		V_{OUT} falling	Fault		91%		
			Good		105%		
	PWRGD Low Voltage	$I(\text{PWRGD}) = 0.33\text{ mA}$			0.3	V	
f_{SW}	Switching frequency	Over V_{IN} and I_{OUT} ranges, RT/CLK pin OPEN	400	500	600	kHz	
f_{CLK}	Synchronization frequency		500		2000	kHz	
$V_{\text{CLK-H}}$	CLK High-Level Threshold	CLK Control		2.2	3.3	V	
$V_{\text{CLK-L}}$	CLK Low-Level Threshold			-0.3	0.4	V	
CLK_PW	CLK Pulse Width			75 ⁽⁴⁾			ns
	Thermal Shutdown	Thermal shutdown		175		$^{\circ}\text{C}$	
		Thermal shutdown hysteresis		15		$^{\circ}\text{C}$	

(1) The minimum V_{IN} depends on V_{OUT} and the switching frequency. Please refer to [Table 9](#) for operating limits.

(2) The stated limit of the set-point voltage tolerance includes the tolerance of both the internal voltage reference and the internal adjustment resistor. The overall output voltage tolerance will be affected by the tolerance of the external R_{SET} resistor.

(3) This control pin has an internal pullup. Do not place an external pull-up resistor on this pin. If this pin is left open circuit, the device operates when input power is applied. A small low-leakage MOSFET is recommended for control. See the application section for further guidance.

(4) The maximum synchronization clock pulse width is dependant on V_{IN} , V_{OUT} , and the synchronization frequency. See the [Synchronization \(CLK\)](#) section for more information.

ELECTRICAL CHARACTERISTICS (continued)

Over -40°C to 85°C free-air temperature, $V_{IN} = 3.3\text{ V}$, $V_{OUT} = 1.8\text{ V}$, $I_{OUT} = 2\text{ A}$,
 $C_{IN1} = 47\text{ }\mu\text{F}$ ceramic, $C_{IN2} = 220\text{ }\mu\text{F}$ poly-tantalum, $C_{OUT1} = 47\text{ }\mu\text{F}$ ceramic, $C_{OUT2} = 100\text{ }\mu\text{F}$ poly-tantalum (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_{IN}	External input capacitance	Ceramic	47 ⁽⁵⁾			μF
		Non-ceramic		220 ⁽⁵⁾		
C_{OUT}	External output capacitance	Ceramic	47 ⁽⁶⁾	150	650 ⁽⁷⁾	μF
		Non-ceramic		100 ⁽⁶⁾	1000 ⁽⁷⁾	
		Equivalent series resistance (ESR)				25

- (5) A minimum of 47 μF of ceramic capacitance is required across the input for proper operation. Locate the capacitor close to the device. An additional 220 μF of bulk capacitance is recommended. See [Table 7](#) for more details.
- (6) The amount of required output capacitance varies depending on the output voltage (see [Table 5](#)). The amount of required capacitance must include at least 47 μF of ceramic capacitance. Locate the capacitance close to the device. Adding additional capacitance close to the load improves the response of the regulator to load transients. See [Table 5](#) and [Table 7](#) for more details.
- (7) When using both ceramic and non-ceramic output capacitance, the combined maximum must not exceed 1200 μF .

5 DEVICE INFORMATION

FUNCTIONAL BLOCK DIAGRAM

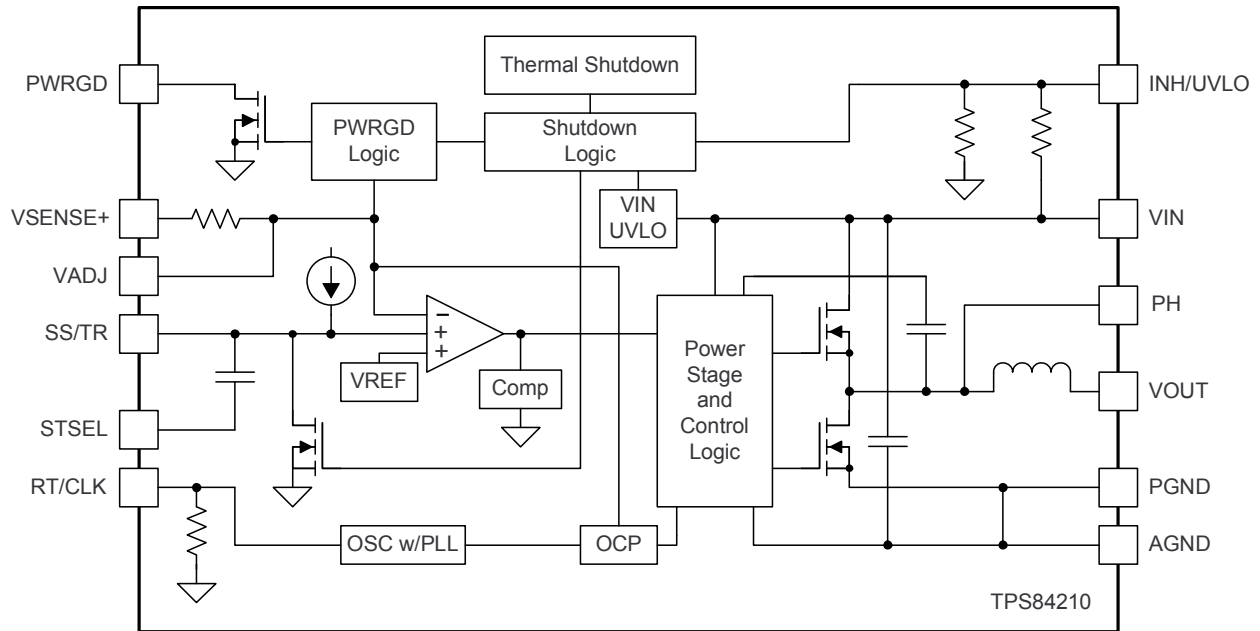
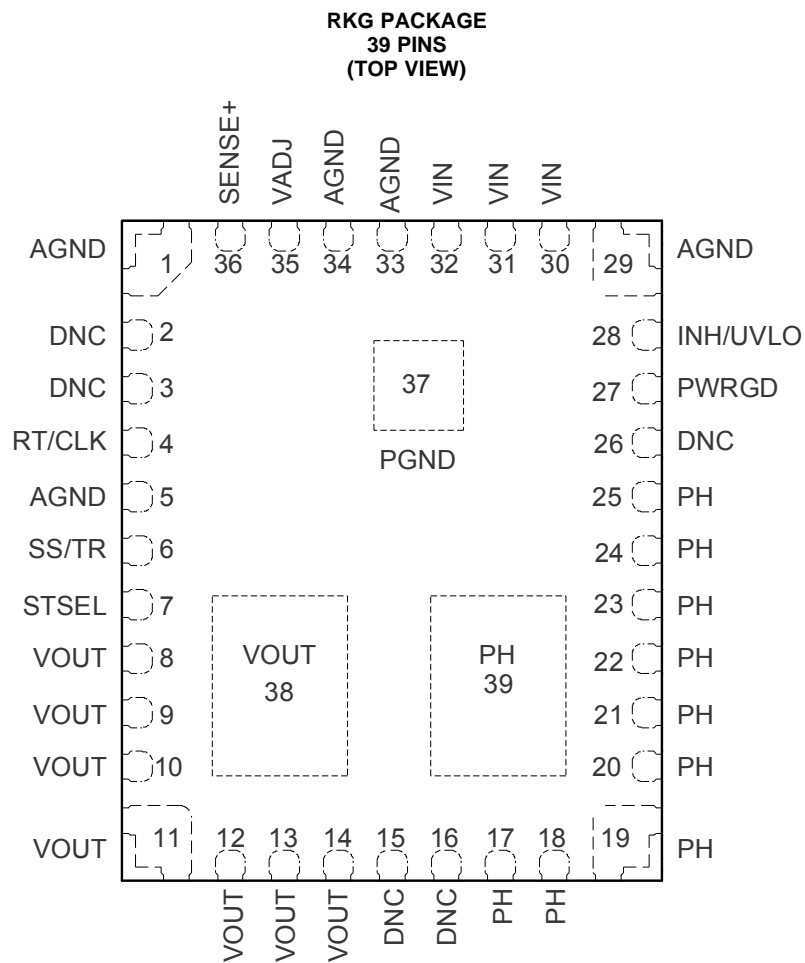
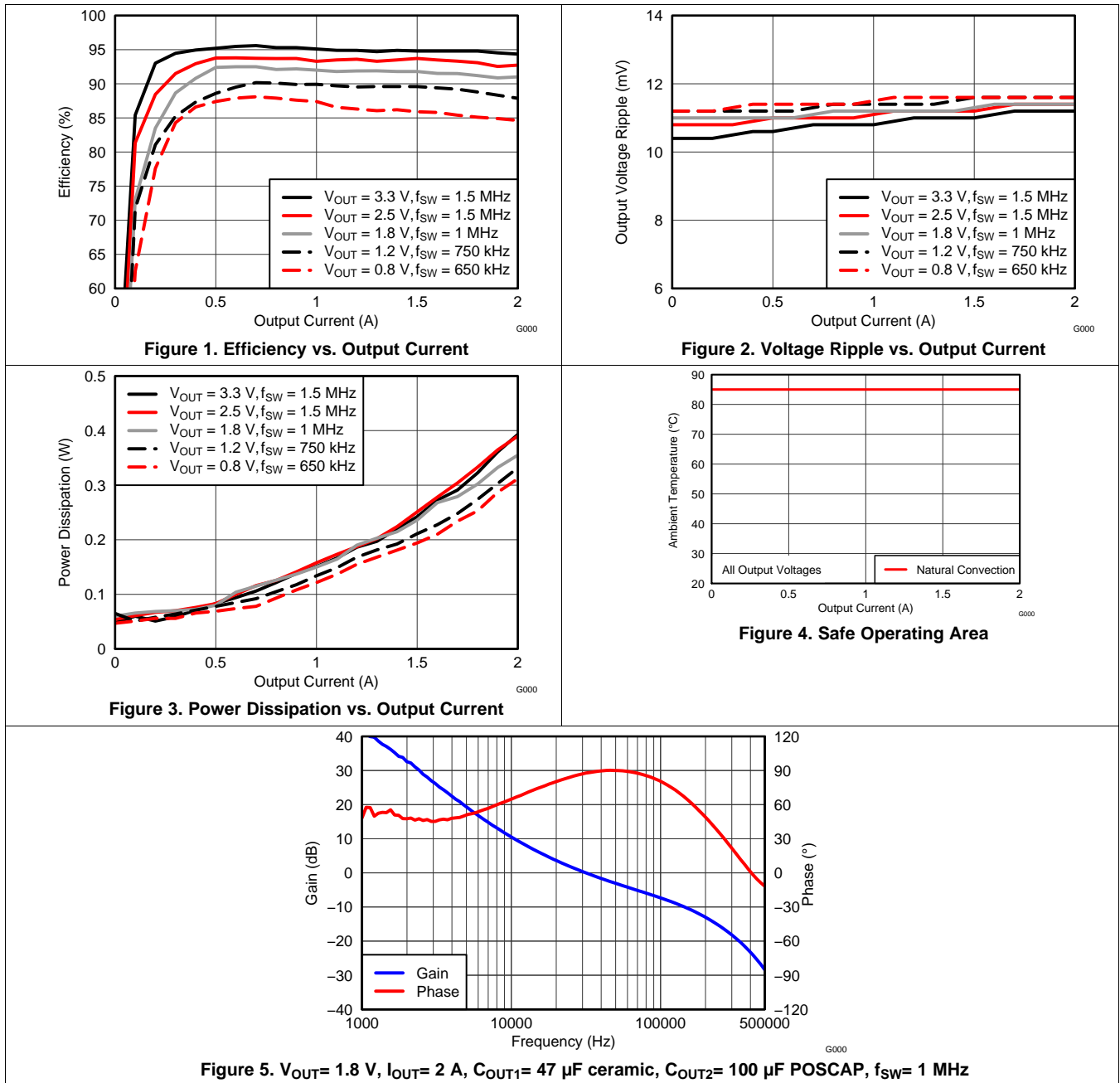


Table 2. PIN DESCRIPTIONS

TERMINAL		DESCRIPTION
NAME	NO.	
AGND	1	Zero VDC reference for the analog control circuitry. These pins should be connected directly to the PCB analog ground plane. Not all pins are connected together internally. All pins must be connected together externally with a copper plane or pour directly under the module. Connect the AGND copper area to the PGND copper area at a single point; directly at the pin 37 PowerPAD using multiple vias. See the recommended layout in Figure 34 .
	5	
	29	
	33	
	34	
PowerPAD (PGND)	37	This pad provides both an electrical and thermal connection to the PCB. This pad should be connected directly to the PCB power ground plane using multiple vias for good electrical and thermal performance. The same vias should also be used to connect to the PCB analog ground plane. See the recommended layout in Figure 34 .
DNC	2	Do Not Connect. Do not connect these pins to AGND, to another DNC pin, or to any other voltage. These pins are connected to internal circuitry. Each pin must be soldered to an isolated pad.
	3	
	15	
	16	
	26	
INH/UVLO	28	Inhibit and UVLO adjust pin. Use an open drain or open collector output logic to control the INH function. A resistor between this pin and AGND adjusts the UVLO voltage.
PH	17	Phase switch node. These pins should be connected by a small copper island under the device for thermal relief. Do not connect any external component to this pin or tie it to a pin of another function.
	18	
	19	
	20	
	21	
	22	
	23	
	24	
25		
39		
PWRGD	27	Power good fault pin. Asserts low if the output voltage is out of tolerance. A pull-up resistor is required.
RT/CLK	4	This pin automatically selects between RT mode and CLK mode. An external timing resistor adjusts the switching frequency of the device. In CLK mode, the device synchronizes to an external clock.
SENSE+	36	Remote sense connection. Connect this pin to VOUT at the load for improved regulation. This pin must be connected to VOUT at the load, or at the module pins.
SS/TR	6	Slow-start and tracking pin. Connecting an external capacitor to this pin adjusts the output voltage rise time. A voltage applied to this pin allows for tracking and sequencing control.
STSEL	7	Slow-start or track feature select. Connect this pin to AGND to enable the internal SS capacitor with a SS interval of approximately 1.1 ms. Leave this pin open to enable the TR feature.
VADJ	35	Connecting a resistor between this pin and AGND sets the output voltage above the 0.8V default voltage.
VIN	30	The positive input voltage power pins, which are referenced to PGND. Connect external input capacitance between these pins and the PGND plane, close to the device.
	31	
	32	
VOUT	8	Output voltage. Connect output capacitors between these pins and the PGND plane, close to the device.
	9	
	10	
	11	
	12	
	13	
	14	
38		

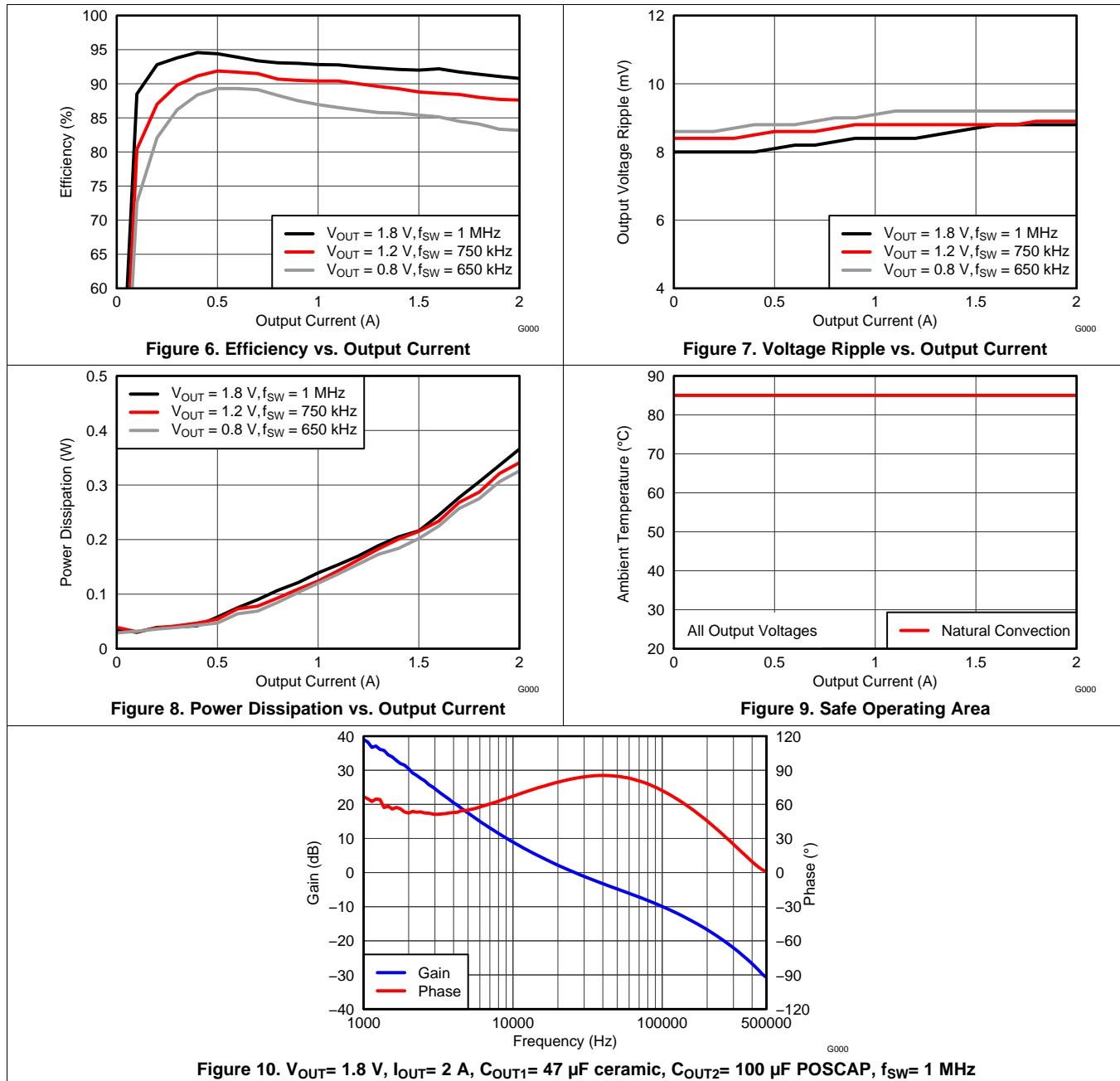


6 TYPICAL CHARACTERISTICS (VIN = 5 V) (1) (2)



- (1) The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to [Figure 1](#), [Figure 2](#), and [Figure 3](#).
- (2) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm double-sided PCB with 1 oz. copper. Applies to [Figure 4](#).

7 TYPICAL CHARACTERISTICS (VIN = 3.3 V) ⁽¹⁾ ⁽²⁾



- (1) The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to [Figure 6](#), [Figure 7](#), and [Figure 8](#).
- (2) The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm double-sided PCB with 1 oz. copper. Applies to [Figure 9](#).

8 APPLICATION INFORMATION

8.1 ADJUSTING THE OUTPUT VOLTAGE

The VADJ control sets the output voltage of the TPS84210. The output voltage adjustment range is from 0.8V to 3.6V. The adjustment method requires the addition of R_{SET}, which sets the output voltage, the connection of SENSE+ to VOUT, and in some cases R_{RT} which sets the switching frequency. The R_{SET} resistor must be connected directly between the VADJ (pin 35) and AGND (pin 33 & 34). The SENSE+ pin (pin 36) must be connected to VOUT either at the load for improved regulation or at VOUT of the module. The R_{RT} resistor must be connected directly between the RT/CLK (pin 4) and AGND (pins 33 & 34).

Table 3 gives the standard external R_{SET} resistor for a number of common bus voltages, along with the recommended R_{RT} resistor for that output voltage.

Table 3. Standard R_{SET} Resistor Values for Common Output Voltages

RESISTORS	OUTPUT VOLTAGE V _{OUT} (V)					
	0.8	1.2	1.5	1.8	2.5	3.3
R _{SET} (kΩ)	open	2.87	1.65	1.15	0.673	0.459
R _{RT} (kΩ)	1200	715	348	348	174	174

For other output voltages, the value of the required resistor can either be calculated using the following formula, or simply selected from the range of values given in Table 4.

$$R_{SET} = \frac{1.43}{\left(\left(\frac{V_{OUT}}{0.803}\right) - 1\right)} \text{ (k}\Omega\text{)} \quad (1)$$

Table 4. Standard R_{SET} Resistor Values

V _{OUT} (V)	R _{SET} (kΩ)	R _{RT} (kΩ)	f _{sw} (kHz)	V _{OUT} (V)	R _{SET} (kΩ)	R _{RT} (kΩ)	f _{sw} (kHz)
0.8	open	1200	650	2.3	0.768	174	1500
0.9	11.8	1200	650	2.4	0.715	174	1500
1.0	5.83	1200	650	2.5	0.673	174	1500
1.1	3.83	1200	650	2.6	0.634	174	1500
1.2	2.87	715	750	2.7	0.604	174	1500
1.3	2.32	715	750	2.8	0.576	174	1500
1.4	1.91	715	750	2.9	0.549	174	1500
1.5	1.65	348	1000	3.0	0.523	174	1500
1.6	1.43	348	1000	3.1	0.499	174	1500
1.7	1.27	348	1000	3.2	0.475	174	1500
1.8	1.15	348	1000	3.3	0.459	174	1500
1.9	1.05	348	1000	3.4	0.442	174	1500
2.0	0.953	174	1500	3.5	0.422	174	1500
2.1	0.845	174	1500	3.6	0.412	174	1500
2.2	0.825	174	1500				

8.2 CAPACITOR RECOMMENDATIONS FOR THE TPS84210 POWER SUPPLY

8.2.1 Capacitor Technologies

8.2.1.1 Electrolytic, Polymer-Electrolytic Capacitors

When using electrolytic capacitors, high-quality, computer-grade electrolytic capacitors are recommended. Polymer-electrolytic type capacitors are recommended for applications where the ambient operating temperature is less than 0°C. The Sanyo OS-CON capacitor series is suggested due to the lower ESR, higher rated surge, power dissipation, ripple current capability, and small package size. Aluminum electrolytic capacitors provide adequate decoupling over the frequency range of 2 kHz to 150 kHz, and are suitable when ambient temperatures are above 0°C.

8.2.1.2 Ceramic Capacitors

The performance of aluminum electrolytic capacitors is less effective than ceramic capacitors above 150 kHz. Multilayer ceramic capacitors have a low ESR and a resonant frequency higher than the bandwidth of the regulator. They can be used to reduce the reflected ripple current at the input as well as improve the transient response of the output.

8.2.1.3 Tantalum, Polymer-Tantalum Capacitors

Polymer-tantalum type capacitors are recommended for applications where the ambient operating temperature is less than 0°C. The Sanyo POSCAP series and Kemet T530 capacitor series are recommended rather than many other tantalum types due to their lower ESR, higher rated surge, power dissipation, ripple current capability, and small package size. Tantalum capacitors that have no stated ESR or surge current rating are not recommended for power applications.

8.2.2 Input Capacitor

The TPS84210 requires a minimum input capacitance of 47 μF of ceramic capacitance. An additional 220 μF polymer-tantalum capacitor is recommended for applications with transient load requirements. The combined ripple current rating of the input capacitors must be at least 1000 mArms. [Table 7](#) includes a preferred list of capacitors by vendor. For applications where the ambient operating temperature is less than 0°C, an additional 1 μF , X5R or X7R ceramic capacitor placed between VIN and AGND is recommended.

8.2.3 Output Capacitor

The required output capacitance is determined by the output voltage of the TPS84210. See [Table 5](#) for the amount of required capacitance. The required output capacitance must include at least one 47 μF ceramic capacitor. For applications where the ambient operating temperature is less than 0°C, an additional 100 μF polymer-tantalum capacitor is recommended. When adding additional non-ceramic bulk capacitors, low-ESR devices like the ones recommended in [Table 7](#) are required. The required capacitance above the minimum is determined by actual transient deviation requirements. See [Table 6](#) for typical transient response values for several output voltage, input voltage and capacitance combinations. [Table 7](#) includes a preferred list of capacitors by vendor.

Table 5. Required Output Capacitance

V _{OUT} RANGE (V)		MINIMUM REQUIRED C _{OUT} (μF)
MIN	MAX	
0.8	< 1.8	147 ⁽¹⁾
1.8	< 3.3	100 ⁽²⁾
3.3	3.6	47 ⁽²⁾

(1) Minimum required must include at least 1 x 47 μF ceramic capacitor plus 1 x 100 μF polymer-tantalum capacitor.

(2) Minimum required must include at least 47 μF of ceramic capacitance.

Table 6. Output Voltage Transient Response

$C_{IN1} = 1 \times 47 \mu\text{F CERAMIC}, C_{IN2} = 220 \mu\text{F POLYMER-TANTALUM}, \text{LOAD STEP} = 1 \text{ A}, 1 \text{ A}/\mu\text{s}$						
V_{OUT} (V)	V_{IN} (V)	C_{OUT1} Ceramic	C_{OUT2} BULK	VOLTAGE DEVIATION (mV)	PEAK-PEAK (mV)	RECOVERY TIME (μs)
0.8	3.3	47 μF	100 μF	30	55	70
		47 μF	330 μF	20	35	70
	5	47 μF	100 μF	30	50	65
		47 μF	330 μF	20	35	65
1.2	3.3	47 μF	100 μF	35	65	65
		47 μF	330 μF	25	50	80
	5	47 μF	100 μF	35	70	65
		47 μF	330 μF	25	45	75
1.8	3.3	47 μF	100 μF	45	80	70
		47 μF	330 μF	35	65	90
	5	47 μF	100 μF	40	65	70
		47 μF	330 μF	35	65	90
2.5	5	47 μF	100 μF	60	100	70
		2x 47 μF	-	75	140	75
3.3	5	47 μF	100 μF	70	130	80
		47 μF	-	90	180	90

Table 7. Recommended Input/Output Capacitors⁽¹⁾

VENDOR	SERIES	PART NUMBER	CAPACITOR CHARACTERISTICS		
			WORKING VOLTAGE (V)	CAPACITANCE (μF)	ESR ⁽²⁾ (m Ω)
Murata	X5R	GRM32ER61C476K	16	47	2
TDK	X5R	C3225X5R0J107M	6.3	100	2
Murata	X5R	GRM32ER60J107M	6.3	100	2
TDK	X5R	C3225X5R0J476K	6.3	47	2
Murata	X5R	GRM32ER60J476M	6.3	47	2
Sanyo	POSCAP	10TPE220ML	10	220	25
Kemet	T520	T520V107M010ASE025	10	100	25
Sanyo	POSCAP	6TPE100MPB	6.3	100	25
Sanyo	POSCAP	2R5TPE220M7	2.5	220	7
Kemet	T530	T530D227M006ATE006	6.3	220	6
Kemet	T530	T530D337M006ATE010	6.3	330	10
Sanyo	POSCAP	2TPF330M6	2.0	330	6
Sanyo	POSCAP	6TPE330MFL	6.3	330	15

(1) Capacitor Supplier Verification

Please verify availability of capacitors identified in this table.

RoHS, Lead-free and Material Details

Please consult capacitor suppliers regarding material composition, RoHS status, lead-free status, and manufacturing process requirements.

(2) Maximum ESR @ 100kHz, 25°C.

8.3 Transient Response

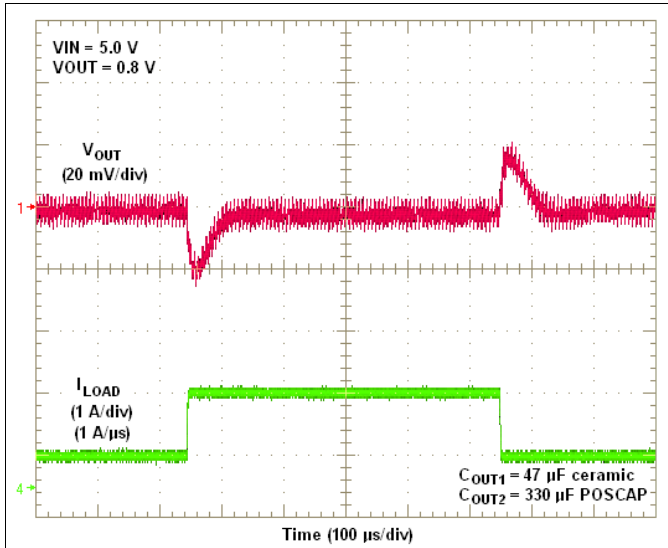


Figure 11. VIN = 5V, VOUT = 0.8V, 1A Load Step

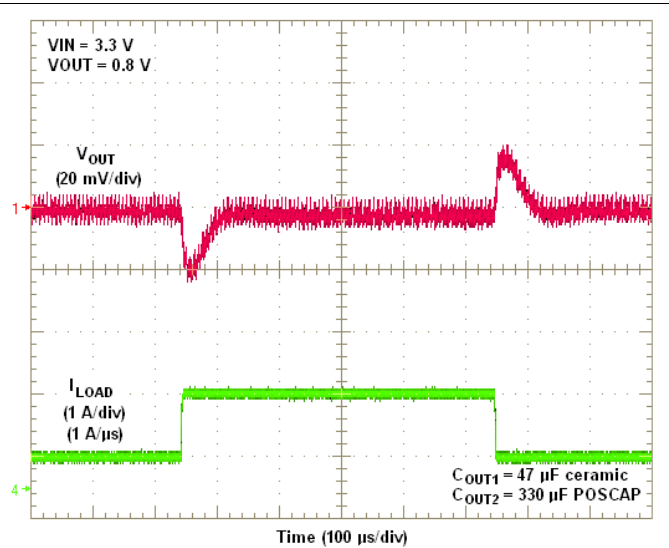


Figure 12. VIN = 3.3V, VOUT = 0.8V, 1A Load Step

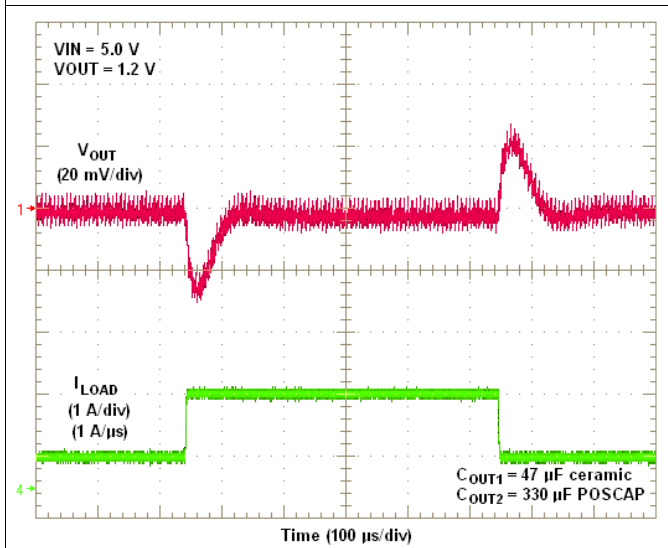


Figure 13. VIN = 5V, VOUT = 1.2V, 1A Load Step

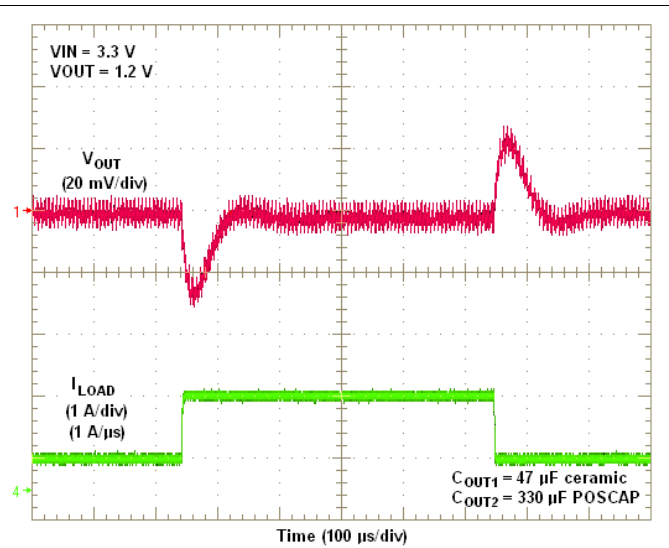
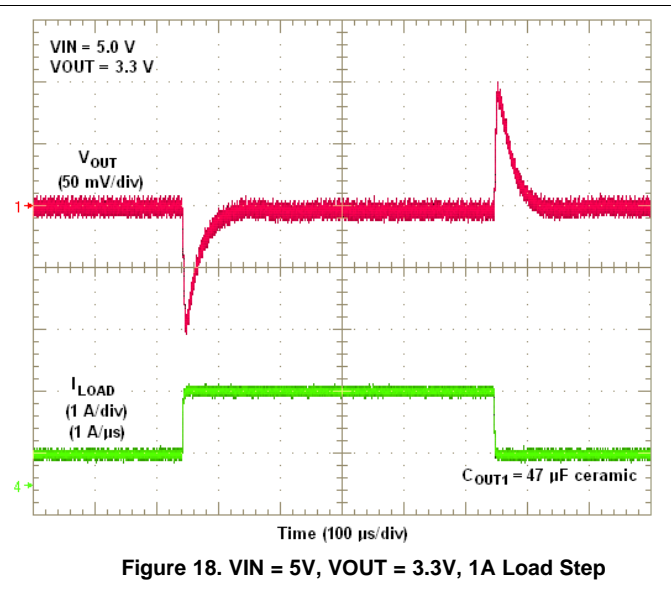
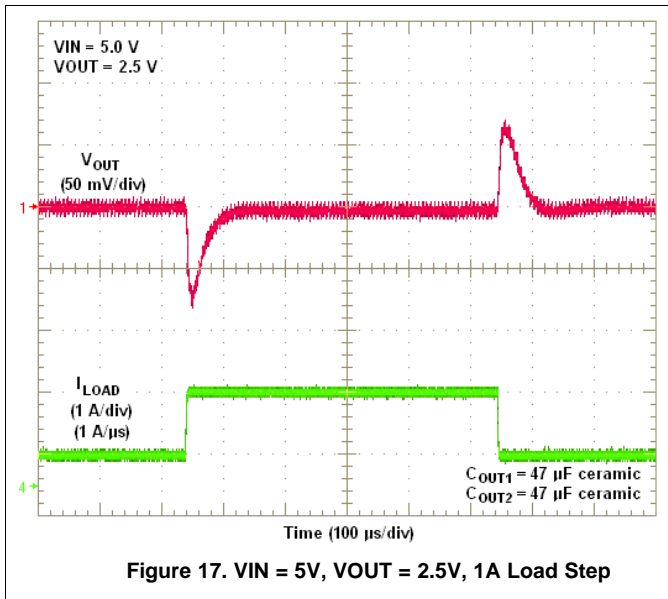
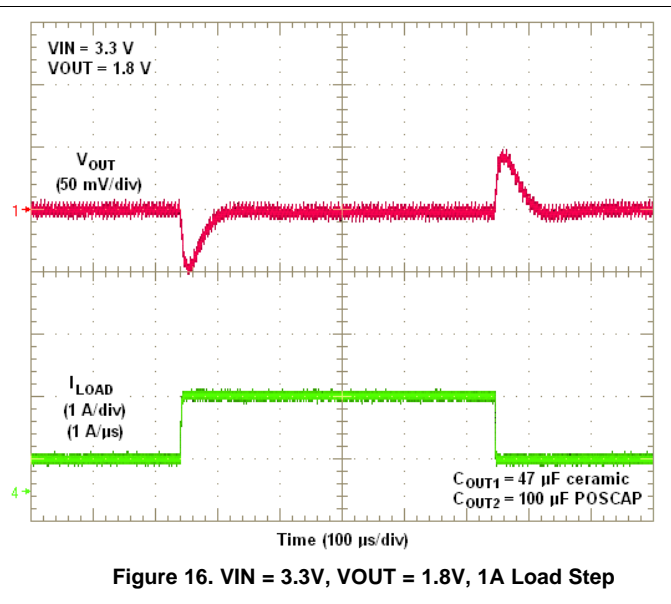
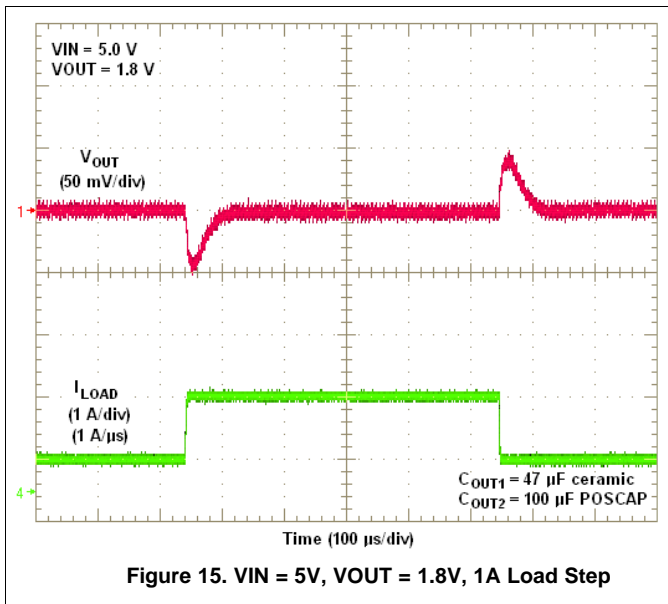


Figure 14. VIN = 3.3V, VOUT = 1.2V, 1A Load Step

Transient Response (continued)



8.4 Application Schematics

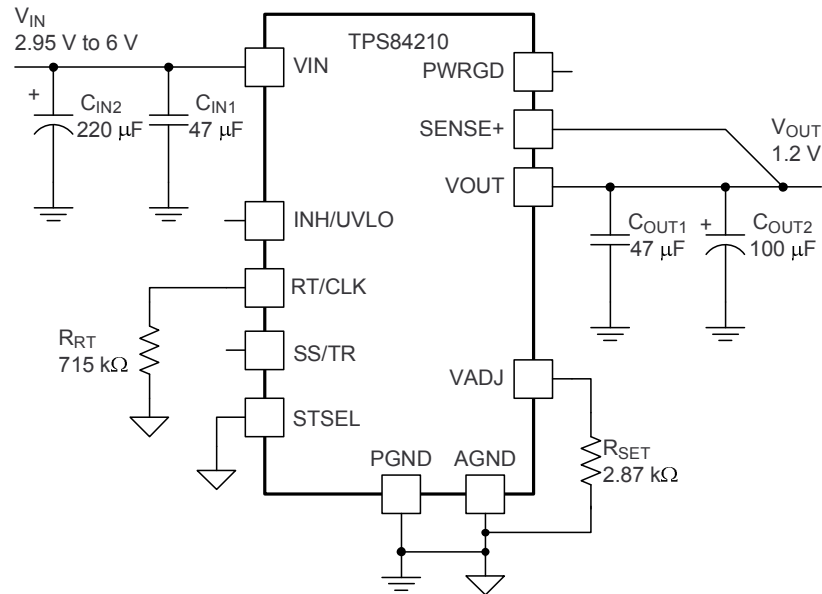


Figure 19. Typical Schematic
 $V_{IN} = 2.95\text{ V to }6.0\text{ V}$, $V_{OUT} = 1.2\text{ V}$

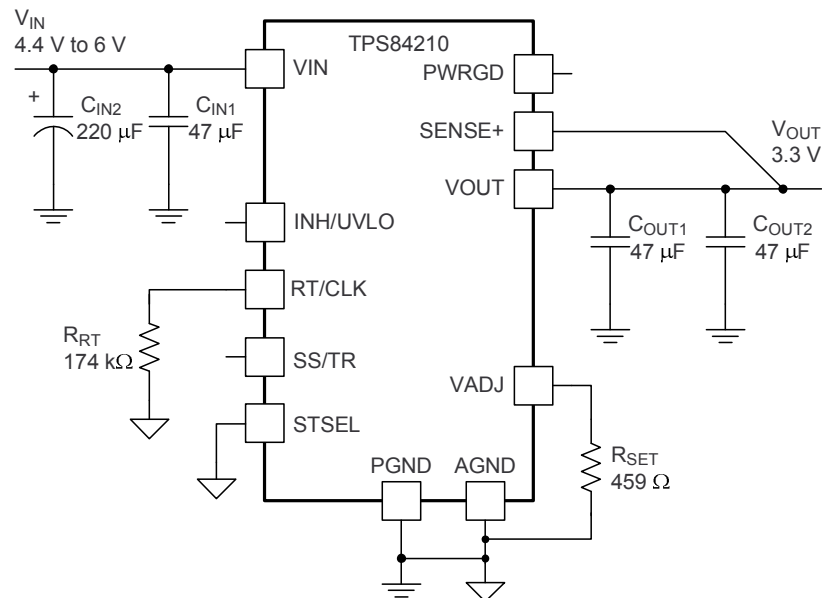


Figure 20. Typical Schematic
 $V_{IN} = 4.4\text{ V to }6.0\text{ V}$, $V_{OUT} = 3.3\text{ V}$

8.5 Power Good (PWRGD)

The PWRGD pin is an open drain output. Once the voltage on the SENSE+ pin is between 93% and 105% of the set voltage, the PWRGD pin pull-down is released and the pin floats. The recommended pull-up resistor value is between 10 k Ω and 100 k Ω to a voltage source that is 6 V or less. The PWRGD pin is in a defined state once VIN is greater than 1.2 V, but with reduced current sinking capability. The PWRGD pin achieves full current sinking capability once the VIN pin is above 2.95V. Figure 21 shows the PWRGD waveform during power-up. The PWRGD pin is pulled low when the voltage on SENSE+ is lower than 91% or greater than 107% of the nominal set voltage. Also, the PWRGD pin is pulled low if the input UVLO or thermal shutdown is asserted, or if the INH pin is pulled low.

8.6 Power-Up Characteristics

When configured as shown in the front page schematic, the TPS84210 produces a regulated output voltage following the application of a valid input voltage. During the power-up, internal soft-start circuitry slows the rate that the output voltage rises, thereby limiting the amount of in-rush current that can be drawn from the input source. The soft-start circuitry introduces a short time delay from the point that a valid input voltage is recognized. Figure 21 shows the start-up waveforms for a TPS84210, operating from a 5-V input and with the output voltage adjusted to 1.8 V. The waveform is measured with a 2-A constant current load.

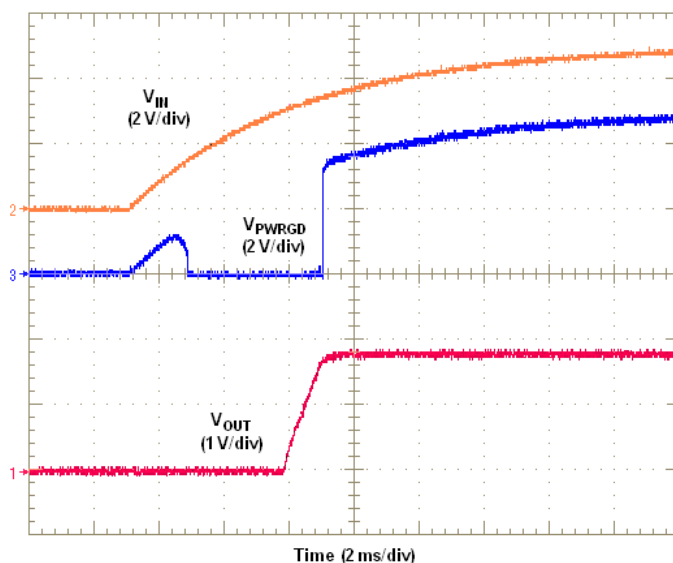


Figure 21. Start-Up Waveforms

8.7 Remote Sense

The SENSE+ pin must be connected to V_{OUT} at the load, or at the device pins.

Connecting the SENSE+ pin to V_{OUT} at the load improves the load regulation performance of the device by allowing it to compensate for any I-R voltage drop between its output pins and the load. An I-R drop is caused by the high output current flowing through the small amount of pin and trace resistance. This should be limited to a maximum of 300 mV.

NOTE

The remote sense feature is not designed to compensate for the forward drop of nonlinear or frequency dependent components that may be placed in series with the converter output. Examples include OR-ing diodes, filter inductors, ferrite beads, and fuses. When these components are enclosed by the SENSE+ connection, they are effectively placed inside the regulation control loop, which can adversely affect the stability of the regulator.

8.8 Output On/Off Inhibit (INH)

The INH pin provides electrical on/off control of the device. Once the INH pin voltage exceeds the threshold voltage, the device starts operation. If the INH pin voltage is pulled below the threshold voltage, the regulator stops switching and enters low quiescent current state.

The INH pin has an internal pull-up current source, allowing the user to float the INH pin for enabling the device. If an application requires controlling the INH pin, use an open drain/collector device, or a suitable logic gate to interface with the pin. Do not place an external pull-up resistor on this pin. Figure 22 shows the typical application of the inhibit function.

Turning Q1 on applies a low voltage to the inhibit control (INH) pin and disables the output of the supply, as shown in Figure 23. If Q1 is turned off, the supply executes a soft-start power-up sequence, as shown in Figure 24. The waveforms were measured with a 2-A constant current load.

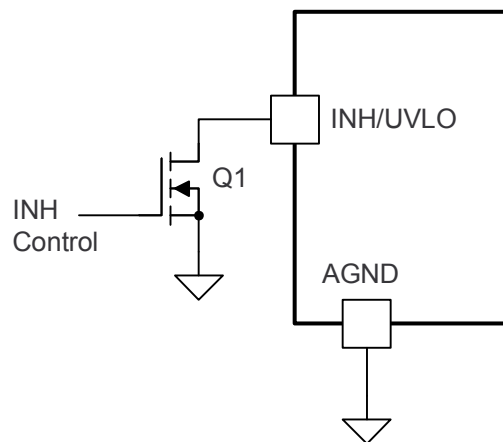
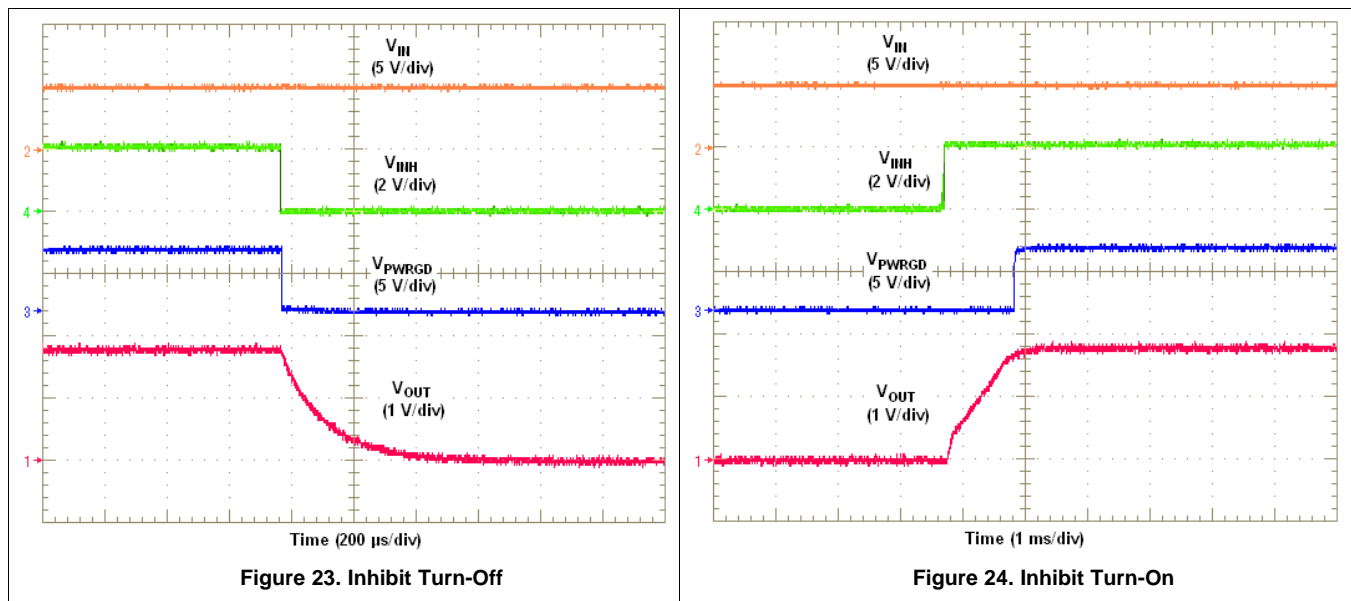


Figure 22. Typical Inhibit Control



8.9 Slow Start (SS/TR)

Connecting the STSEL pin to AGND and leaving SS/TR pin open enables the internal SS capacitor with a slow start interval of approximately 1.1 ms. Adding additional capacitance between the SS pin and AGND increases the slow start time. Table 8 shows an additional SS capacitor connected to the SS/TR pin and the STSEL pin connected to AGND. See Table 8 below for SS capacitor values and timing interval.

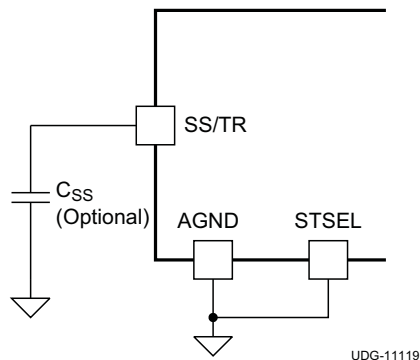


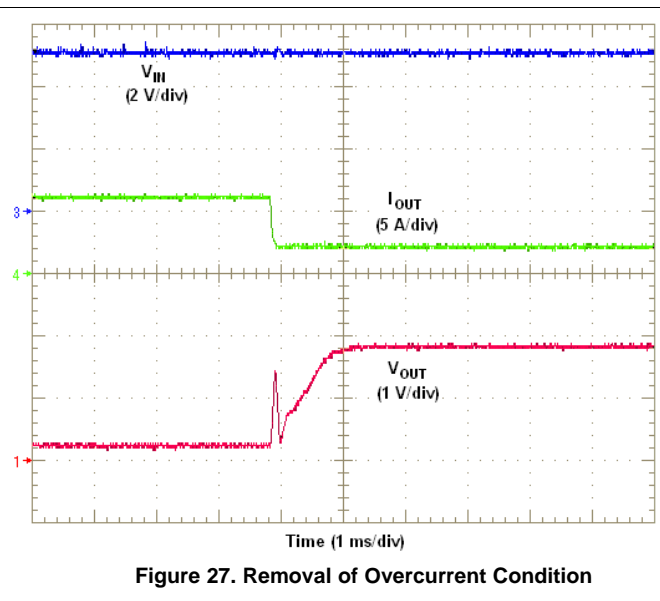
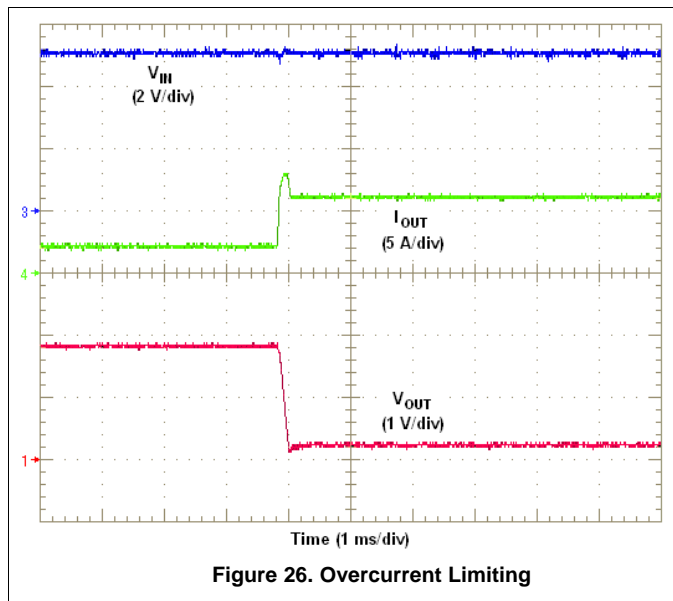
Figure 25. Slow-Start Capacitor (C_{SS}) and STSEL Connection

Table 8. Slow-Start Capacitor Values and Slow-Start Time

C_{SS} (pF)	open	2200	4700	10000	15000	22000	25000
SS Time (msec)	1.1	1.9	2.8	4.6	6.4	8.8	9.8

8.10 Overcurrent Protection

For protection against load faults, the TPS84210 uses current limiting. The device is protected from overcurrent conditions by cycle-by-cycle current limiting and frequency foldback. During an overcurrent condition the output current is limited and the output voltage is reduced, as shown in Figure 26. When the overcurrent condition is removed, the output voltage returns to the established voltage, as shown in Figure 27.



8.11 Synchronization (CLK)

An internal phase locked loop (PLL) has been implemented to allow synchronization between 500 kHz and 2 MHz, and to easily switch from RT mode to CLK mode. To implement the synchronization feature, connect a square wave clock signal to the RT/CLK pin with a minimum pulse width of 75 ns. The maximum clock pulse width must be calculated using Equation 2. The clock signal amplitude must transition lower than 0.4 V and higher than 2.2 V. The start of the switching cycle is synchronized to the falling edge of RT/CLK pin. In applications where both RT mode and CLK mode are needed, the device can be configured as shown in Figure 28.

Before the external clock is present, the device works in RT mode and the switching frequency is set by RT resistor (R_{RT}). When the external clock is present, the CLK mode overrides the RT mode. The device switches from RT mode to CLK mode and the RT/CLK pin becomes high impedance as the PLL starts to lock onto the frequency of the external clock. The device will lock to the external clock frequency approximately 15 μ s after a valid clock signal is present. It is not recommended to switch from CLK mode back to RT mode because the internal switching frequency drops to a lower frequency before returning to the switching frequency set by the RT resistor.

$$CLK_PW_{MAX} = \frac{0.75 \times \left(1 - \frac{V_{OUT}}{V_{IN(min)}} \right)}{f_{SW}} \quad (2)$$

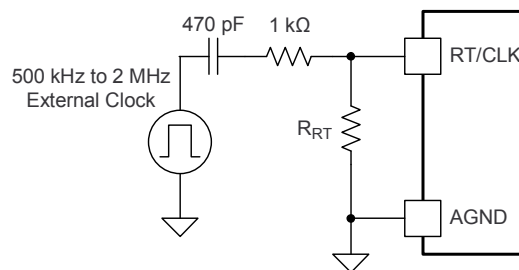


Figure 28. CLK/RT Configuration

The synchronization frequency must be selected based on the output voltages of the devices being synchronized. Table 9 shows the allowable frequencies for a given range of output voltages based on a resistive load. 5-V input applications requiring 1.5 A or less can synchronize to a wider frequency range. For the most efficient solution, always synchronize to the lowest allowable frequency. For example, an application requires synchronizing three TPS84210 devices with output voltages of 1.2V@1.7A, 1.8@1.1A and 3.3V@ 1.0A, all powered from $V_{IN} = 5V$. Table 9 shows that all three output voltages can be synchronized to any frequency between 700 kHz to 1 MHz. For best efficiency, choose 700 kHz as the synchronization frequency.

Table 9. Synchronization Frequency vs Output Voltage

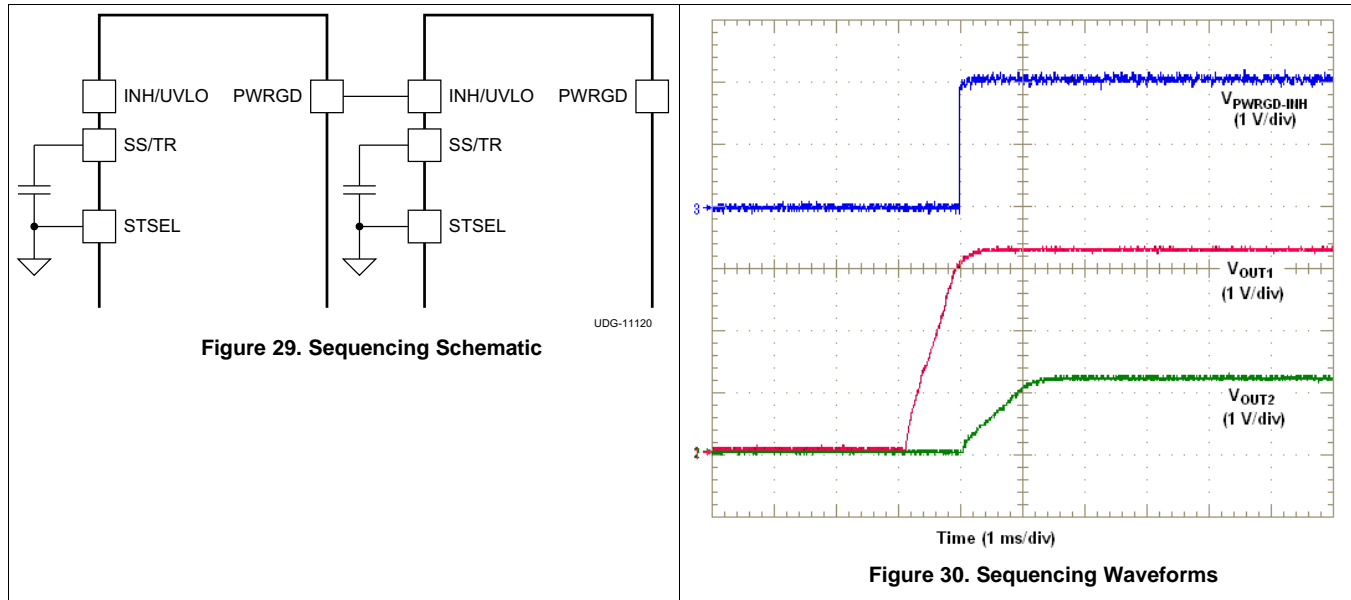
SYNCHRONIZATION FREQUENCY (kHz)	R_{RT} (k Ω)	$V_{IN} = 5 V$				$V_{IN} = 3.3 V$	
		$I_{OUT} \leq 1.5 A$		$I_{OUT} > 1.5 A$		All I_{OUT}	
		V_{OUT} RANGE (V)		V_{OUT} RANGE (V)		V_{OUT} RANGE (V)	
		MIN	MAX	MIN	MAX	MIN	MAX
500	open	0.8	1.4	0.8	0.8	0.8	1.1
550	3400	0.8	1.6	0.8	0.9	0.8	1.2
600	1800	0.8	1.9	0.8	1.1	0.8	2.0
650	1200	0.8	2.4	0.8	1.2	0.8	2.2
700	887	0.8	3.6	0.8	1.3	0.8	2.4
750	715	0.9	3.6	0.9	1.5	0.8	2.5
800	590	0.9	3.6	0.9	1.7	0.8	2.5
900	511	1.0	3.6	1.0	2.2	0.8	2.5
1000	348	1.2	3.6	1.2	2.5	0.8	2.5
1250	232	1.4	3.6	1.4	3.3	1.0	2.5
1500	174	1.7	3.6	1.7	3.6	1.1	2.5
1750	137	2.0	3.6	2.0	3.6	1.3	2.4

Table 9. Synchronization Frequency vs Output Voltage (continued)

SYNCHRONIZATION FREQUENCY (kHz)	R _{RT} (kΩ)	VIN = 5 V				VIN = 3.3 V	
		I _{OUT} ≤ 1.5 A		I _{OUT} > 1.5 A		All I _{OUT}	
		V _{OUT} RANGE (V)		V _{OUT} RANGE (V)		V _{OUT} RANGE (V)	
		MIN	MAX	MIN	MAX	MIN	MAX
2000	113	2.3	3.6	2.3	3.6	1.5	2.3

8.12 Sequencing (SS/TR)

Many of the common power supply sequencing methods can be implemented using the SS/TR, INH and PWRGD pins. The sequential method is illustrated in [Figure 29](#) using two TPS84210 devices. The PWRGD pin of the first device is coupled to the INH pin of the second device which enables the second power supply once the primary supply reaches regulation. Do not place a pull-up resistor on PWRGD in this configuration. [Figure 30](#) shows sequential turn-on waveforms of two TPS84210 devices.



Simultaneous power supply sequencing can be implemented by connecting the resistor network of R1 and R2 shown in [Figure 31](#) to the output of the power supply that needs to be tracked or to another voltage reference source. [Figure 32](#) shows simultaneous turn-on waveforms of two TPS84210 devices. Use [Equation 3](#) and [Equation 4](#) to calculate the values of R1 and R2.

$$R1 = \frac{(V_{OUT2} \times 12.6)}{0.803} \text{ (k}\Omega\text{)} \quad (3)$$

$$R2 = \frac{0.803 \times R1}{(V_{OUT2} - 0.803)} \text{ (k}\Omega\text{)} \quad (4)$$

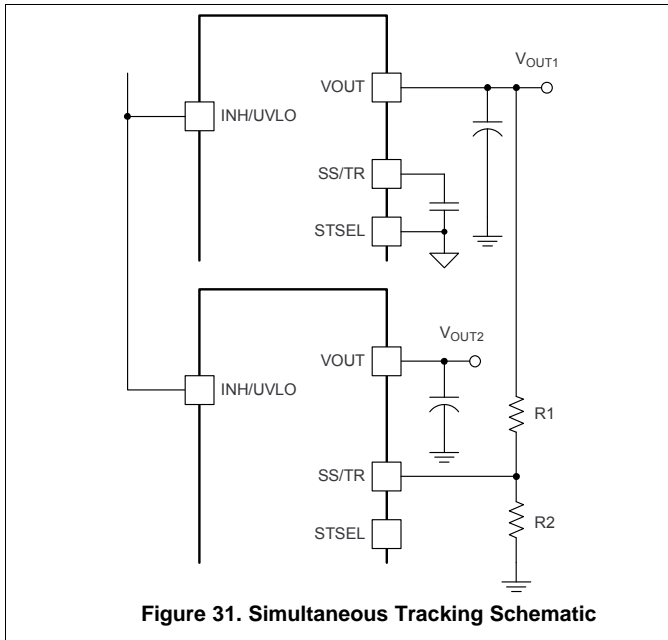


Figure 31. Simultaneous Tracking Schematic

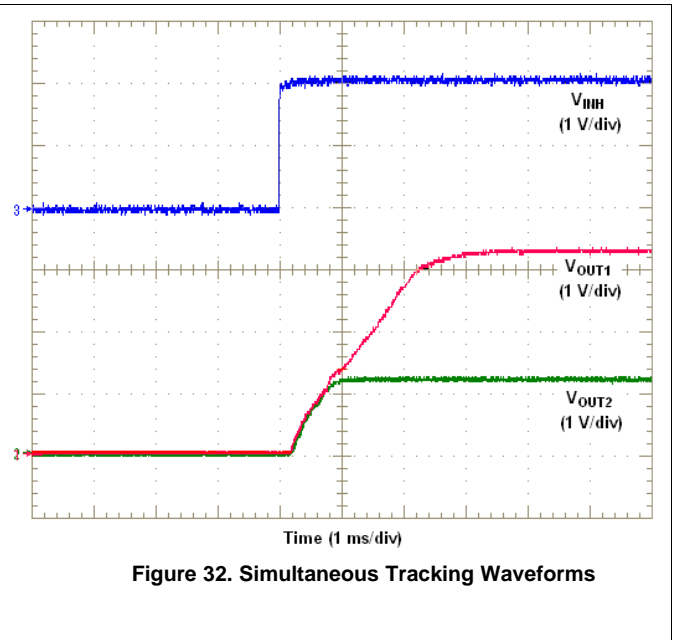


Figure 32. Simultaneous Tracking Waveforms

8.13 Programmable Undervoltage Lockout (UVLO)

The TPS84210 implements internal UVLO circuitry on the VIN pin. The device is disabled when the VIN pin voltage falls below the internal VIN UVLO threshold. The internal VIN UVLO rising threshold is 3.135 V (max) with a typical hysteresis of 300 mV.

If an application requires a higher UVLO threshold on the VIN pin, the UVLO pin can be configured as shown in Figure 33. Table 10 lists standard values for R_{UVLO} to adjust the VIN UVLO voltage up.

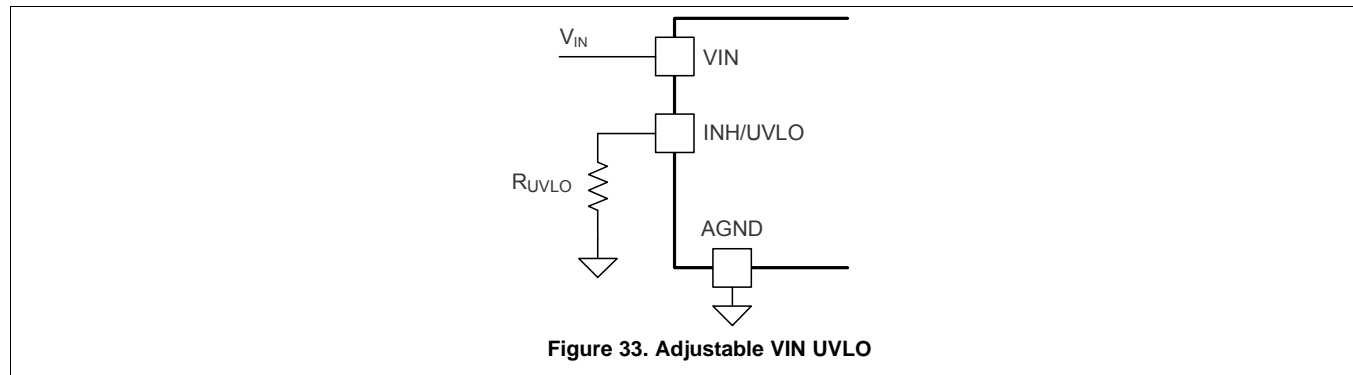


Table 10. Standard Resistor values for Adjusting VIN UVLO

VIN UVLO (V) (typ)	3.25	3.5	3.75	4.0	4.25	4.5	4.75
R_{UVLO} (k Ω)	294	133	86.6	63.4	49.9	42.2	35.7
Hysteresis (mV)	325	335	345	355	365	375	385

8.14 Thermal Shutdown

The internal thermal shutdown circuitry forces the device to stop switching if the junction temperature exceeds 175°C typically. The device reinitiates the power up sequence when the junction temperature drops below 160°C typically.

8.15 Layout Considerations

To achieve optimal electrical and thermal performance, an optimized PCB layout is required. Figure 34, shows a typical PCB layout. Some considerations for an optimized layout are:

- Use large copper areas for power planes (VIN, VOUT, and PGND) to minimize conduction loss and thermal stress.
- Place ceramic input and output capacitors close to the module pins to minimize high frequency noise.
- Locate additional output capacitors between the ceramic capacitor and the load.
- Place a dedicated AGND copper area beneath the TPS84210.
- Connect the AGND and PGND copper area at one point; directly at the pin 37 PowerPad using multiple vias.
- Place R_{SET} , R_{RT} , and C_{SS} as close as possible to their respective pins.
- Use multiple vias to connect the power planes to internal layers.

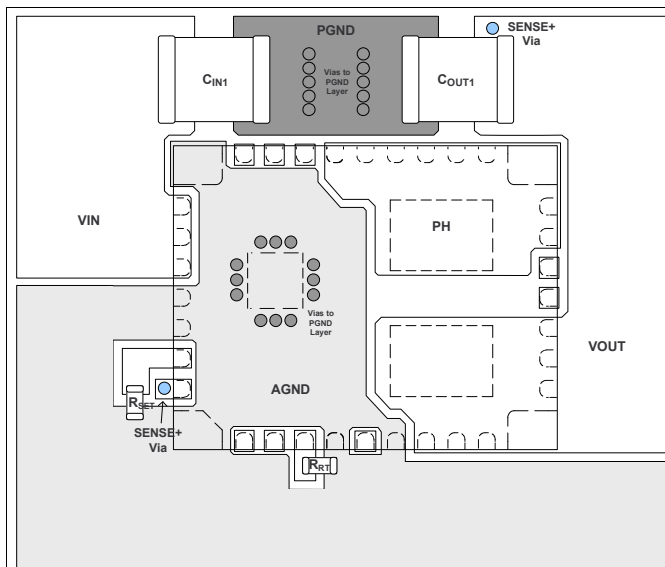


Figure 34. Typical Top-Layer Recommended Layout

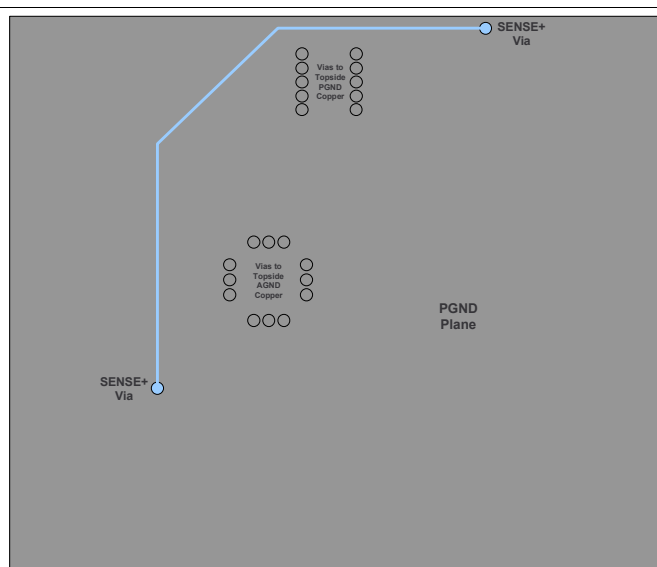


Figure 35. Typical PGND-Layer Recommended Layout

8.16 EMI

The TPS84210 is compliant with EN55022 Class B radiated emissions. Figure 36 and Figure 37 show typical examples of radiated emissions plots for the TPS84210 operating from 5V and 3.3V respectively. Both graphs include the plots of the antenna in the horizontal and vertical positions.

EMI (continued)

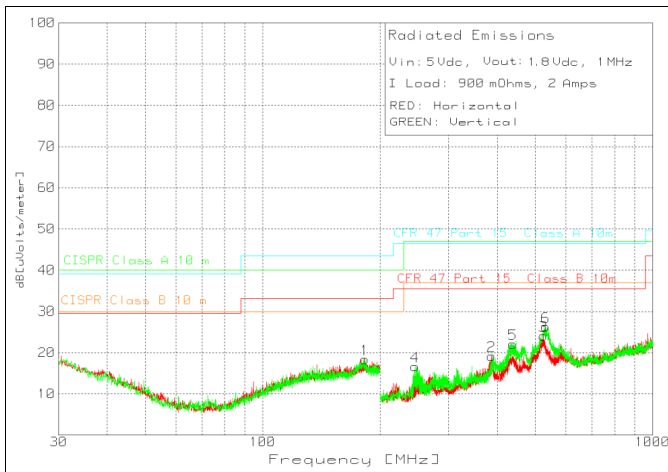


Figure 36. Radiated Emissions 5-V Input, 1.8-V Output, 2-A Load (EN55022 Class B)

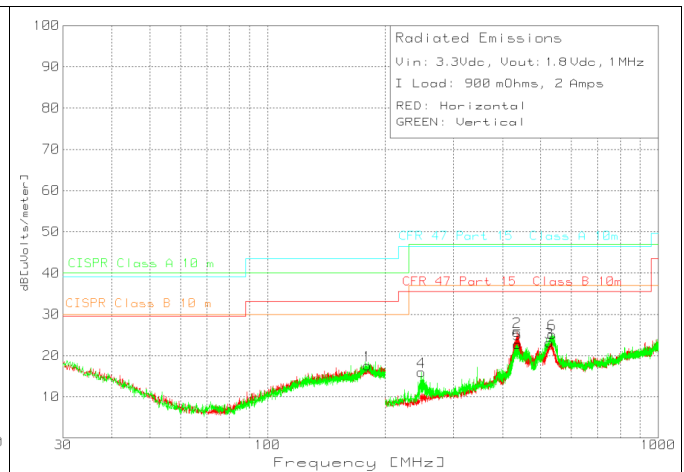


Figure 37. Radiated Emissions 3.3-V Input, 1.8-V Output, 2-A Load (EN55022 Class B)

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision A (March 2012) to Revision B	Page
---	-------------

- Added peak reflow and maximum number of reflows information [2](#)
-

Changes from Original (SEPTEMBER 2011) to Revision A	Page
---	-------------

- Adjusted voltage levels in [Table 9](#) [20](#)
-

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TPS84210RKGR	ACTIVE	B1QFN	RKG	39	500	RoHS Exempt & Green	CU NIPDAU	Level-3-240C-1 YEAR	-40 to 85	(54218, TPS84210)	Samples
TPS84210RKGT	ACTIVE	B1QFN	RKG	39	250	RoHS Exempt & Green	CU NIPDAU	Level-3-240C-1 YEAR	-40 to 85	(54218, TPS84210)	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

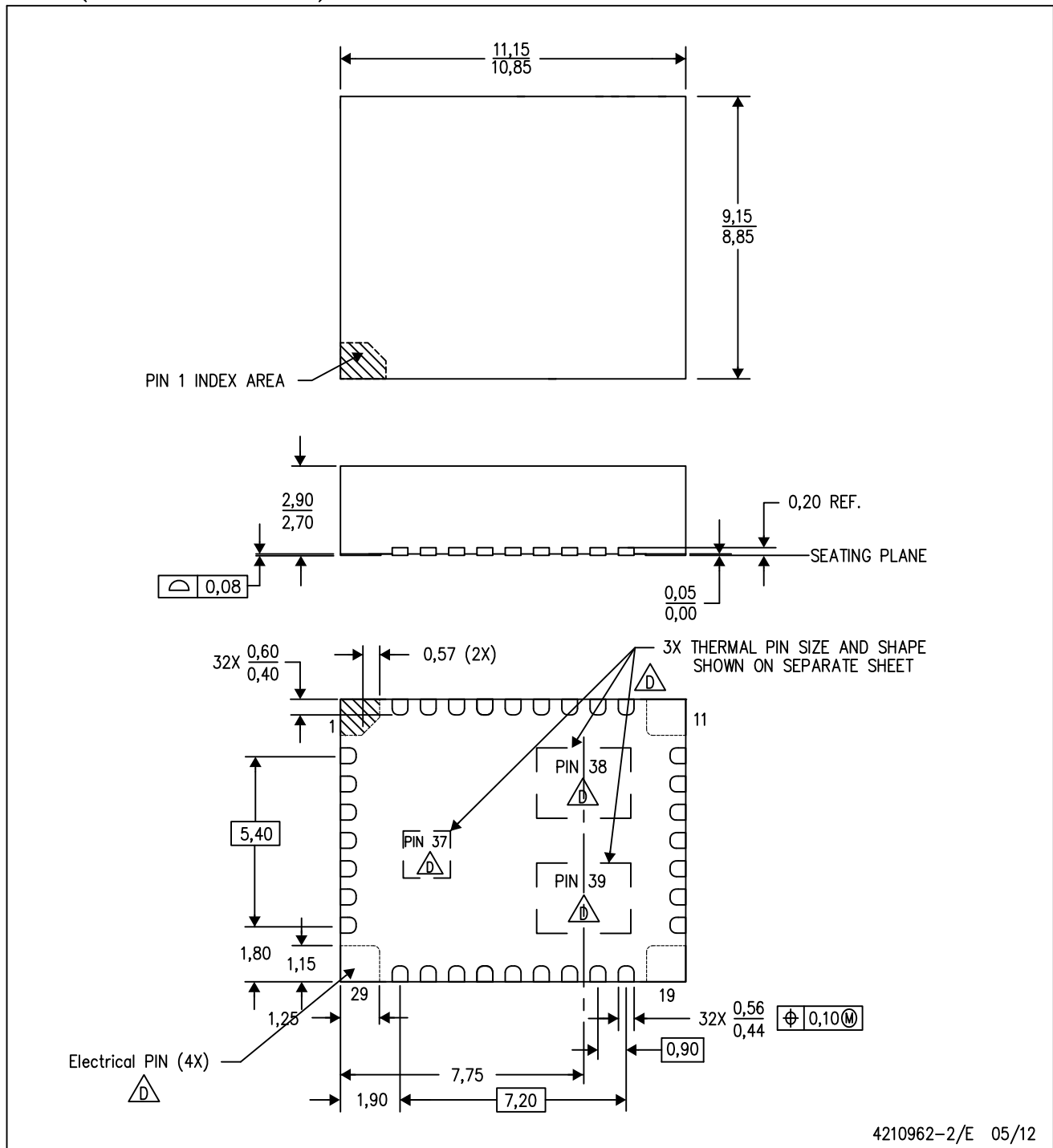
Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



MECHANICAL DATA

RKG (R-PB1QFN-N39)

PLASTIC QUAD FLATPACK NO-LEAD

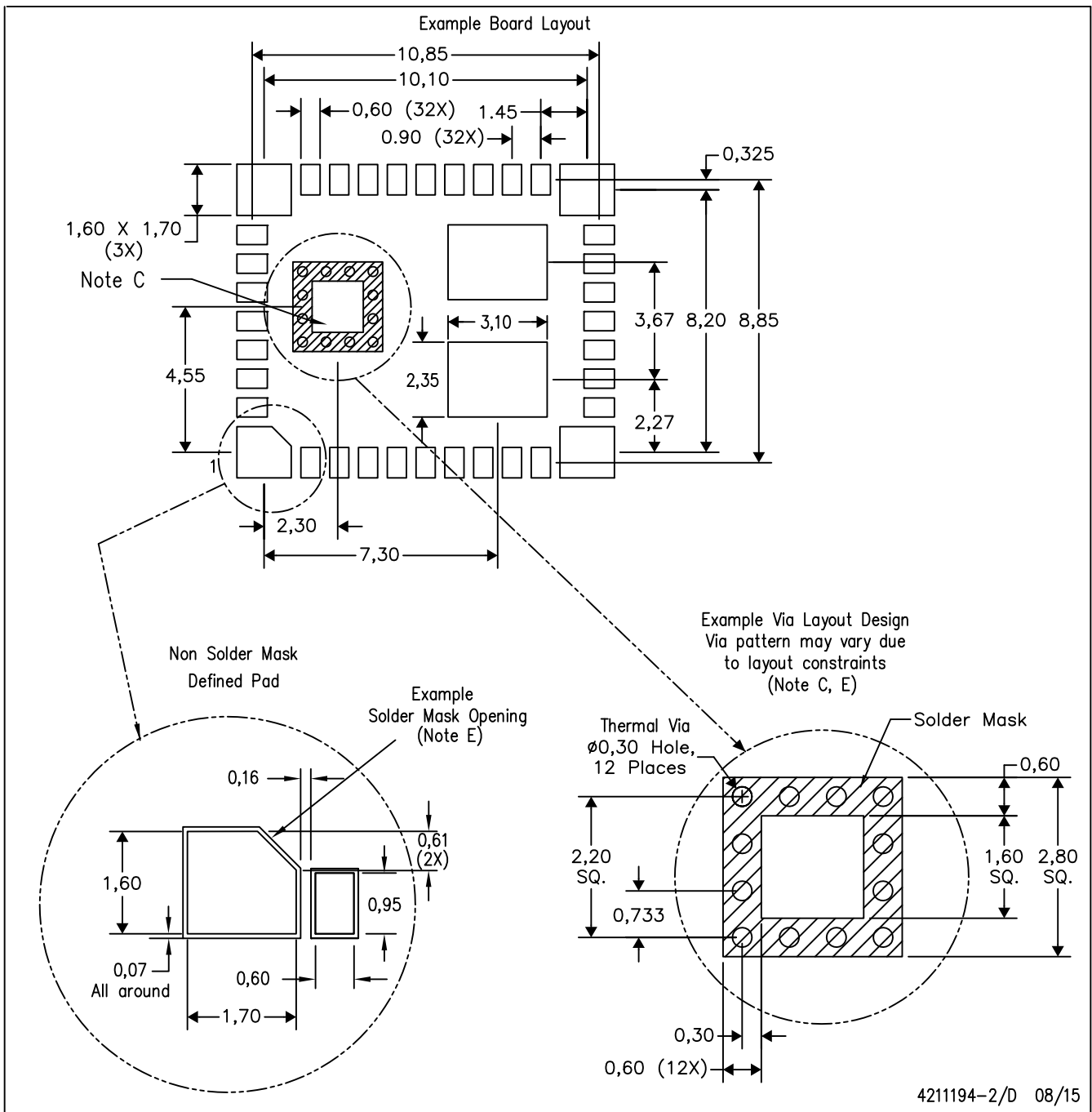


4210962-2/E 05/12

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Quad Flatpack, No-leads (QFN) package configuration.
 -  D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 -  F. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane.

RKG (S-PB1QFN-N39)

PLASTIC QUAD FLATPACK NO-LEAD

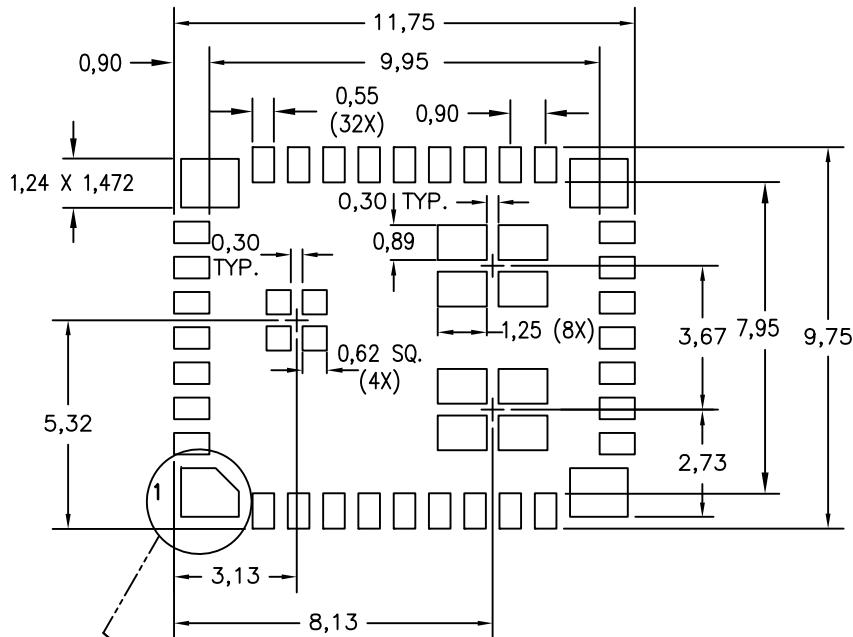


- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - E. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

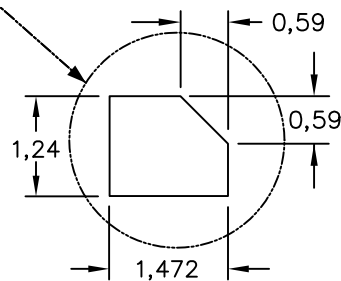
RKG (S-PB1QFN-N39)

PLASTIC QUAD FLATPACK NO-LEAD

Example Stencil Design (Note D)
Stencil Thickness = 0,125mm



60% solder coverage on thermal pads



4211194-3/D 08/15

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - E. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

重要声明

德州仪器 (TI) 公司有权按照最新发布的 JESD46 对其半导体产品和服务进行纠正、增强、改进和其他修改，并不再按最新发布的 JESD48 提供任何产品和服务。买方在下订单前应获取最新的相关信息，并验证这些信息是否完整且是最新的。

TI 公布的半导体产品销售条款 (<http://www.ti.com/sc/docs/stdterms.htm>) 适用于 TI 已认证和批准上市的已封装集成电路产品的销售。另有其他条款可能适用于其他类型 TI 产品及服务的使用或销售。

复制 TI 数据表上 TI 信息的重要部分时，不得变更该等信息，且必须随附所有相关保证、条件、限制和通知，否则不得复制。TI 对该等复制文件不承担任何责任。第三方信息可能受到其它限制条件的制约。在转售 TI 产品或服务时，如果存在对产品或服务参数的虚假陈述，则会失去相关 TI 产品或服务的明示或暗示保证，且构成不公平的、欺诈性商业行为。TI 对此类虚假陈述不承担任何责任。

买方和在系统中整合 TI 产品的其他开发人员（总称“设计人员”）理解并同意，设计人员在设计应用时应自行实施独立的分析、评价和判断，且应全权负责并确保应用的安全性，及设计人员的应用（包括应用中使用的 TI 产品）应符合所有适用的法律法规及其他相关要求。设计人员就自己设计的应用声明，其具备制订和实施下列保障措施所需的一切必要专业知识，能够 (1) 预见故障的危险后果，(2) 监视故障及其后果，以及 (3) 降低可能导致危险的故障几率并采取适当措施。设计人员同意，在使用或分发包含 TI 产品的任何应用前，将彻底测试该等应用和和该等应用所用 TI 产品的功能而设计。

TI 提供技术、应用或其他设计建议、质量特点、可靠性数据或其他服务或信息，包括但不限于与评估模块有关的参考设计和材料（总称“TI 资源”），旨在帮助设计人员开发整合了 TI 产品的应用，如果设计人员（个人，或如果是代表公司，则为设计人员的公司）以任何方式下载、访问或使用任何特定的 TI 资源，即表示其同意仅为该等目标，按照本通知的条款使用任何特定 TI 资源。

TI 所提供的 TI 资源，并未扩大或以其他方式修改 TI 对 TI 产品的公开适用的质保及质保免责声明；也未导致 TI 承担任何额外的义务或责任。TI 有权对其 TI 资源进行纠正、增强、改进和其他修改。除特定 TI 资源的公开文档中明确列出的测试外，TI 未进行任何其他测试。

设计人员只有在开发包含该等 TI 资源所列 TI 产品的应用时，才被授权使用、复制和修改任何相关单项 TI 资源。但并未依据禁止反言原则或其他法律授予您任何 TI 知识产权的任何其他明示或默示的许可，也未授予您 TI 或第三方的任何技术或知识产权的许可，该等许可包括但不限于任何专利权、版权、屏蔽作品权或与应用 TI 产品或服务的任何整合、机器制作、流程相关的其他知识产权。涉及或参考了第三方产品或服务的信息不构成使用此类产品或服务的许可或与其相关的保证或认可。使用 TI 资源可能需要您向第三方获得对该等第三方专利或其他知识产权的许可。

TI 资源系“按原样”提供。TI 兹免除对资源及其使用作出所有其他明确或默示的保证或陈述，包括但不限于对准确性或完整性、产权保证、无屡发故障保证，以及适销性、适合特定用途和不侵犯任何第三方知识产权的任何默认保证。TI 不负责任何申索，包括但不限于因组合产品所致或与之有关的申索，也不为或对设计人员进行辩护或赔偿，即使该等产品组合已列于 TI 资源或其他地方。对因 TI 资源或其使用引起或与之有关的任何实际的、直接的、特殊的、附带的、间接的、惩罚性的、偶发的、从属或惩戒性损害赔偿，不管 TI 是否获悉可能会产生上述损害赔偿，TI 概不负责。

除 TI 已明确指出特定产品已达到特定行业标准（例如 ISO/TS 16949 和 ISO 26262）的要求外，TI 不对未达到任何该等行业标准要求而承担任何责任。

如果 TI 明确宣称产品有助于功能安全或符合行业功能安全标准，则该等产品旨在帮助客户设计和创作自己的符合相关功能安全标准和要求的的应用。在应用内使用产品的行为本身不会配有 任何安全特性。设计人员必须确保遵守适用于其应用的相关安全要求和标准而设计。设计人员不可将任何 TI 产品用于关乎性命的医疗设备，除非已由各方获得授权的管理人员签署专门的合同对此类应用专门作出规定。关乎性命的医疗设备是指出现故障会导致严重身体伤害或死亡的医疗设备（例如生命保障设备、心脏起搏器、心脏除颤器、人工心脏泵、神经刺激器以及植入设备）。此类设备包括但不限于，美国食品药品监督管理局认定为 III 类设备的设备，以及在美国以外的其他国家或地区认定为同等类别设备的所有医疗设备。

TI 可能明确指定某些产品具备某些特定资格（例如 Q100、军用级或增强型产品）。设计人员同意，其具备一切必要专业知识，可以为自己的应用选择适合的产品，并且正确选择产品的风险由设计人员承担。设计人员单方面负责遵守与该等选择有关的所有法律或监管要求。

设计人员同意向 TI 及其代表全额赔偿因其不遵守本通知条款和条件而引起的任何损害、费用、损失和/或责任。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2018 德州仪器半导体技术（上海）有限公司